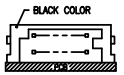
PRODUCT NO.

94898

PRODUCT NO. 94898-XXXX	STAND OFF DIM"W"(mm)	SOLDER TAIL	DIM "P" (mm)	DIM "Q" (mm)	FOR LOWER DECK OR UPPER DECK	③ HOLD DOWN	SHEET NO.	MOUNTIMG STYLE TO PCB
000	0	R/A	2.8	-//-	LOWER	NONE	NO.2	TOP MOUNT 94898-0XXX
000LF	0	R/A	2.8	-//-	LOWER	NONE		
000MLF	0	R/A	2.8	-//-	LOWER	NONE		
000H	0	R/A	2.8	-//-	LOWER	YES		
000HLF	0	R/A	2.8	-//-	LOWER	YES		
001	0	SMT STAGGERED	-//-	-//-	LOWER	NONE		
001LF	0	SMT STAGGERED	-//-	-//-	LOWER	NONE		
001H	0	SMT STAGGERED	-//-	-//-	LOWER	YES		
001HLF	0	SMT STAGGERED	-//-	-//-	LOWER	YES		
002	0	SMT IN LINE	-//-	-//-	LOWER	NONE		
002LF	0	SMT IN LINE	-//-	-//-	LOWER	NONE		
002H	0	SMT IN LINE	-//-	-//-	LOWER	YES		
002HLF	0	SMT IN LINE	-//-	-//-	LOWER	YES		
010	4	R/A	2.8	-//-	LOWER	NONE	NO.3	
010LF	4	R/A	2.8	-//-	LOWER	NONE		
020	5	R/A	2.8	-//-	LOWER	NONE		
020LF	5	R/A	2.8	-//-	LOWER	NONE		
020MLF	5	R/A	2.8	-//-	LOWER	NONE		
021MLF	5	R/A	2.8	-//-	LOWER	NONE		
040	2	R/A	2.5	-//-	LOWER	NONE		
040MLF	2	R/A	2.5		LOWER	NONE		
040LF	2	R/A	2.5	-//-	LOWER	NONE		
005	FOR 0	R/A	2.8	8.6	UPPER	NONE	NO.4	
005LF	FOR 0	R/A	2.8	8.6	UPPER	NONE		
045	FOR 2	R/A	2.5	10.3	UPPER	NONE		
045MLF	FOR 2	R/A	2.5	10.3	UPPER	NONE		
045LF	FOR 2	R/A	2.5	10.3	UPPER	NONE		
500	0	R/A	2.8	-//-	LOWER	NONE	NO.5	BOTTOM MOUNT 94898-5XXX
500LF	0	R/A	2.8	-//-	LOWER	NONE		
500H	0	R/A	2.8	-//-	LOWER	YES		
500HLF	0	R/A	2.8	-//-	LOWER	YES		
501	0	SMT STAGGERED	-//-	-//-	LOWER	NONE		
501LF	0	SMT STAGGERED	-//-	-//-	LOWER	NONE		
501H	0	SMT STAGGERED	-//-	-//-	LOWER	YES		
501HLF	0	SMT STAGGERED	-//-	-//-	LOWER	YES		
502	0	SMT IN LINE	-//-	-//-	LOWER	NONE		
502J	0	SMT IN LINE	-//-	-//-	LOWER	NONE		
502LF	0	SMT IN LINE	-//-	-//-	LOWER	NONE		
502H	0	SMT IN LINE	-//-	-//-	LOWER	YES		
502HLF	0	SMT IN LINE	-//-	-//-	LOWER	YES		
510	4	R/A	2.8	-//-	LOWER	NONE	NO.6	
510LF	4	R/A	2.8	-//-	LOWER	NONE		
520	5	R/A	2.8	-//-	LOWER	NONE		
520LF	5	R/A	2.8	-//-	LOWER	NONE		
530	2	R/A	1.48	-//-	LOWER	NONE		
530LF	2	R/A	1.48	-//-	LOWER	NONE		
540	2	R/A	2.5	-//-	LOWER	NONE		
540LF	2	R/A	2.5	-//-	LOWER	NONE		
505	FOR 0	R/A	2.8	8.6	UPPER	NONE	NO.7	
505LF	FOR 0	R/A	2.8	8.6	UPPER	NONE		
535	FOR 2	R/A	1.48	9.28	UPPER	NONE		
535LF	FOR 2	R/A	1.48	9.28	UPPER	NONE		
545	FOR 2	R/A	2.5	10.3	UPPER	NONE		
545LF	FOR 2	R/A	2.5	10.3	UPPER	NONE		

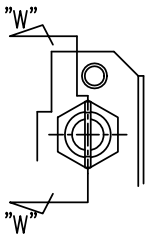


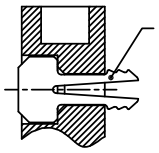
NOTES

1. PRODUCT SPEC:110-263

94898-X X X X X X

- OPTIONAL LEED FREE — NONE : N □ / LF : YES
- OPTIONAL HOLD DOWN — NONE : N □ / H : YES (SEE FIGURE □F -xxxH)
- LOW COST VERSION — NONE : N □ / M : YES (DETAIL AS COMPONENT)
- SOLDER TAIL — 0 : R/A (FOR LOWER & SINGLE) / 1 : SMT STAGGERED (FOR LOWER □NLY) / 2 : SMT IN LINE (FOR LOWER □NLY) / 5 : R/A (FOR UPPER □NLY)
- STAND OFF — 0 : 0mm / 1 : 4mm / 2 : 5mm / 3 : 2mm (SPECIAL TAIL LENGTH) / 4 : 2mm
- MOUNTING STYLE — 0 : TOP MOUNTING / 5 : BOTTOM MOUNTING





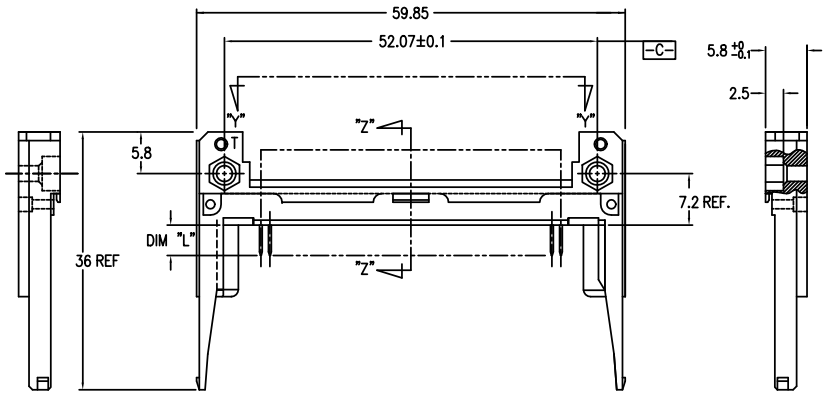
SECTION "W"-"W"

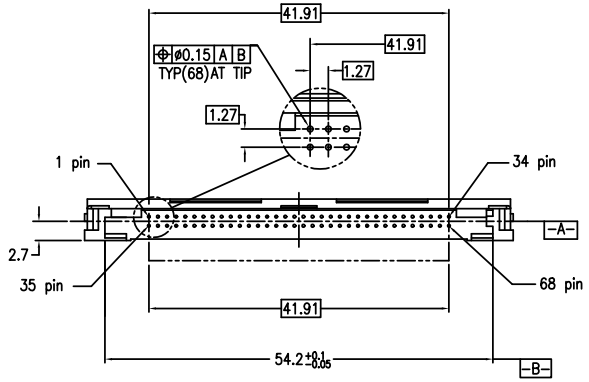
94898-xxxH
(OPTIONAL HOLD DOWN)

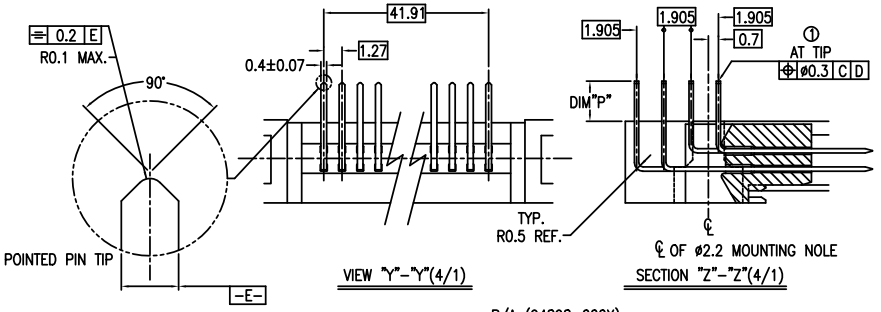
mat'l. code				surface ISO 1302	tolerance ISO 406 ISO 1101	projection	product family PCMCIA
ltr	ecn no	dr	date	tolerances unless otherwise specified			title
J	N06-0065	M.Z	04/02'06	angles	0.X±0.3	MM	68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE
K	N07-0219	M.Z	12/07'07	linear	0.XX±0.13		
L	N08-0041	M.Z	03/10'08	±2°	0.XXX±0.05	scale 1:1	
M	N08-0219	M.Z	10/10'08	dr M.Hasegawa 2/24/05			dwg no 94898 sheet 1 of 7 size A4
N	N09-0045	SH	05/25/09	engr M.Hasegawa 2/24/05			
P	ELX-N-007954	ZK	11/01/11	chr			
				appd			type CUSTOMER Drawing

sheet	revision	P	P	P	P	P	P	P									
index	sheet	1	2	3	4	5	6	7									

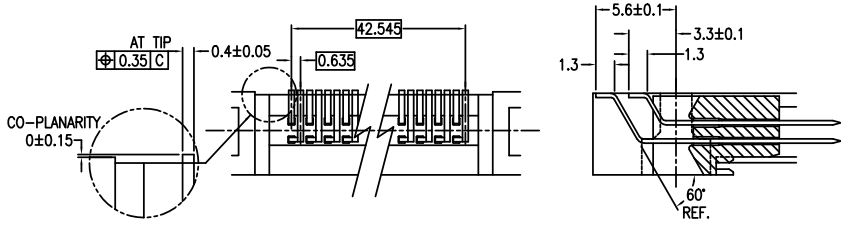
PRODUCT NO.
94898-000
94898-000LF
94898-000H
94898-000HLF
94898-000MLF
94898-001
94898-001LF
94898-001H
94898-001HLF
94898-002
94898-002LF
94898-002H
94898-002HLF



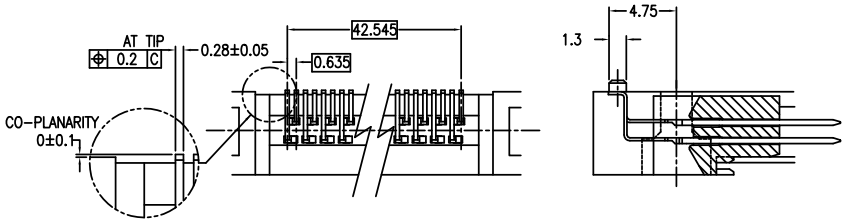




R/A (94898-000X)



SMT STAGGERED (94898-001X)



SMT IN LINE (94898-002X)

NOTES

① TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
2. SEE TA-946 FOR PCB LAYOUT.
③ MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC
PIN : COPPER ALLOY.
HOLD-DOWN : BRASS
④ FINISH
PIN
UNDER PLATING : 0.5um MIN. Ni.
CONTACT AREA : 0.1um MIN. Au.
OVER 0.5um MIN. Pd-Ni.
SOLDER AREA : 2.5um MIN. Sn-Pb.
OR 2.5um MIN. PURE Sn.(FOR -XXXLF)
HOLD-DOWN : 2.5um MIN. PURE Sn.
5. RECOMMENDED PCB HOLE (OPTIONAL HOLD-DOWN) : 2.3±0.1
6. SEQUENCE PIN ASSIGNMENT

	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
PIN No.	OTHERS	36.67	1,17,34 35,51,68

7. GENERAL TOLERANCE : ±0.3
8. SEE SHEET 1 REGARDING COMPONENTS.
9. IF LEAD FREE P/N,THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
10. LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
11. IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION

mat'l code				surface ISO 1302	tolerance ISO 406 ISO 1101	projection	product family PCMCIA		
ltr	ecn no	dr	date	tolerances unless otherwise specified			title		
P				angles	linear 0.X±0.3	MM	68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE		
				±2°	0.XX±0.13	scale 1:1			
				dr M.Hasegawa 2/24/'05	0.XXX±0.05		dwg no 94898	sheet 2 of 7	size A4
				engr M.Hasegawa 2/24/'05					
				chr			type CUSTOMER		Drawing
				appd					
sheet index	revision sheet								

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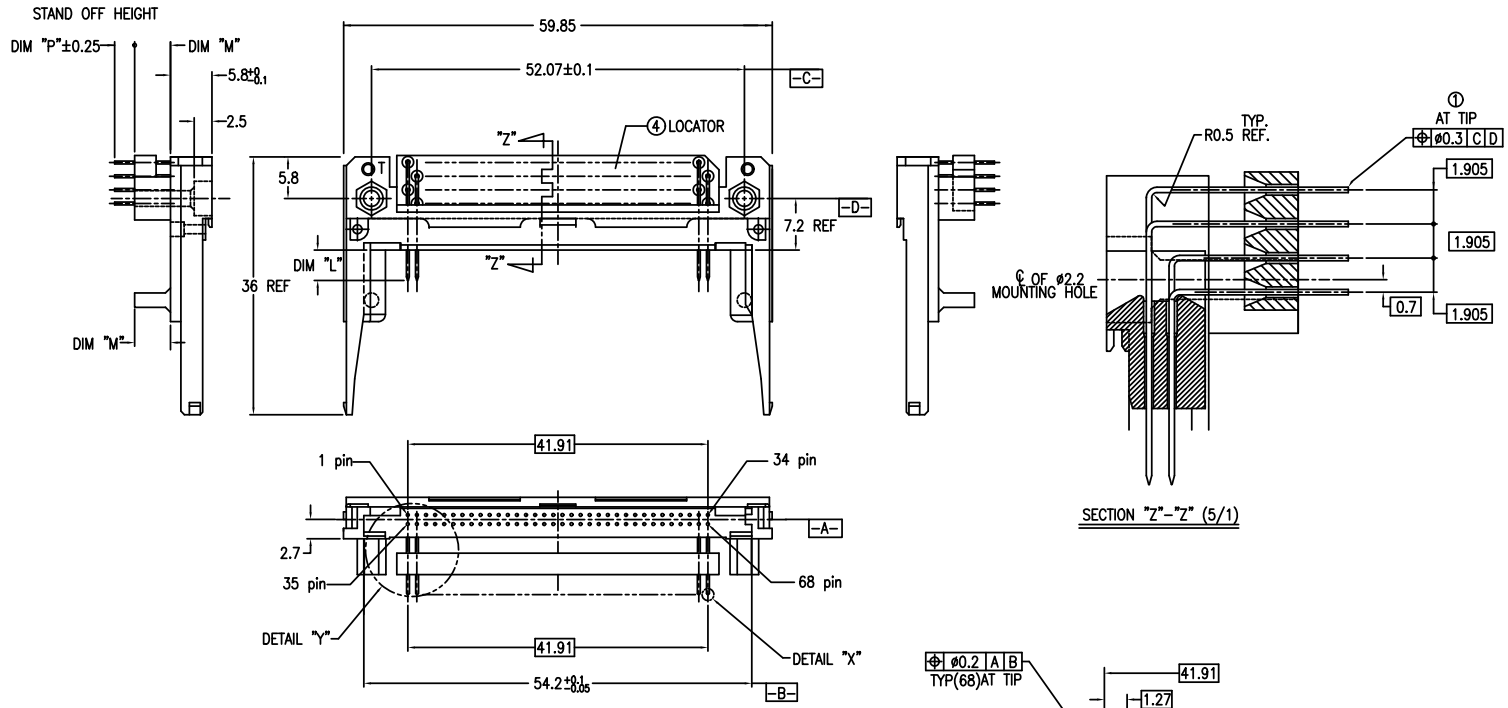
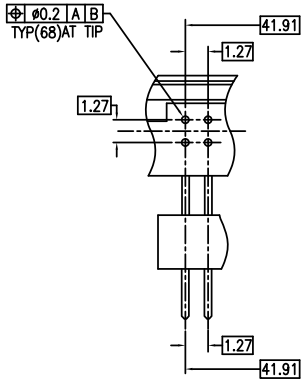
form A3

PDS: Rev :P STATUS: Released Printed: Dec 19, 2011

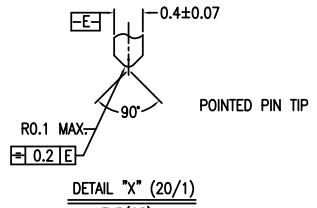
PRODUCT NO.
94898-010
94898-010LF
94898-020/020M
94898-020LF/020MLF
94898-021MLF
94898-040
94898-040LF/040MLF



SECTION "Z"-"Z" (5/1)



DETAIL "Y" (5/1)



DETAIL "X" (20/1)
TYP(68)

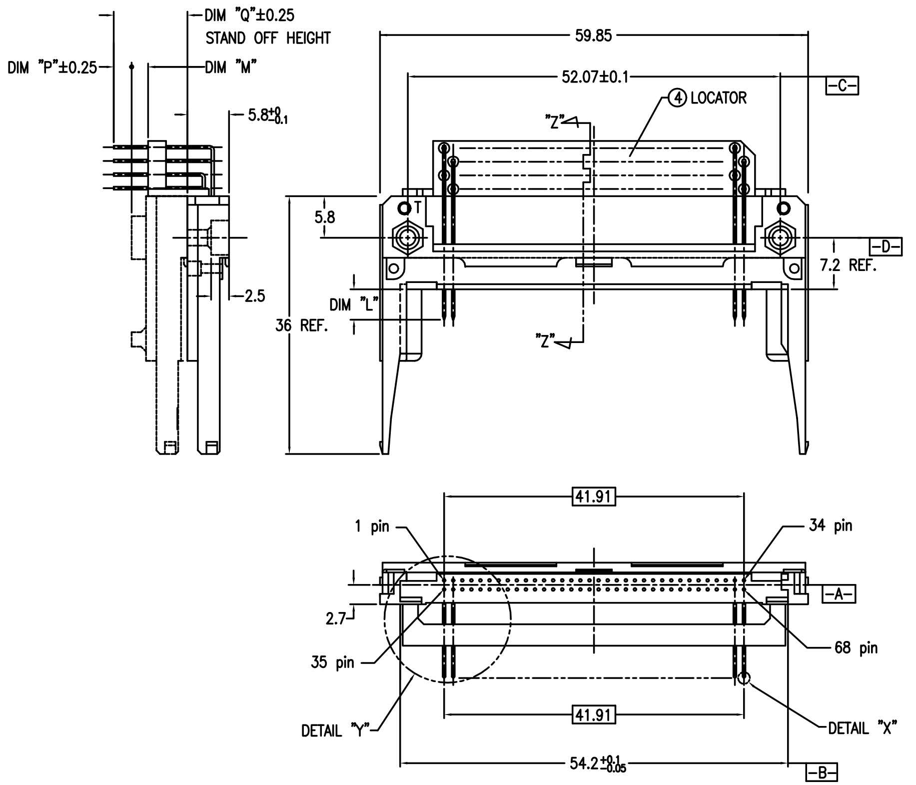
① TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
2. SEE TA-946 FOR PCB LAYOUT.
③ MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC
PIN : COPPER ALLOY.
HOLD-DOWN : BRASS
④ FINISH
PIN
UNDER PLATING : 0.5um MIN. Ni.
CONTACT AREA : 0.1um MIN. Au.
OVER 0.5um MIN. Pd-Ni.
SOLDER AREA : 2.5um MIN. Sn-Pb.
OR 2.5um MIN. PURE Sn.(FOR -XXXLF)
HOLD-DOWN : 2.5um MIN. PURE Sn.
5. RECOMMENDED PCB HOLE (OPTIONAL HOLD-DOWN) : 2.3±0.1
6. SEQUENCE PIN ASSIGNMENT

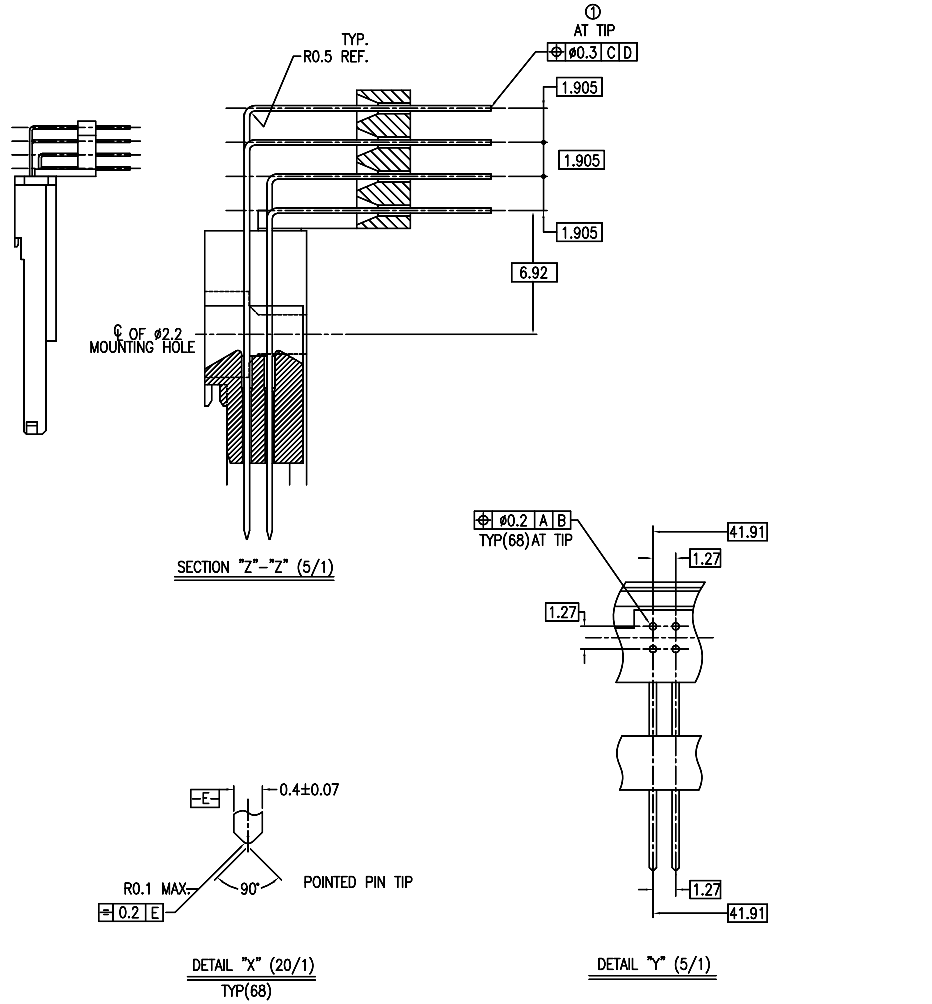
	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
PIN No.	OTHERS	36.67	1,17,34 35,51,68

7. GENERAL TOLERANCE : ±0.3
8. SEE SHEET 1 REGARDING COMPONENTS.
9. IF LEAD FREE P/N,THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
10. LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
11. IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION
12 "M" SHOWS IT IS LOW COST VERSION,IT IS OPTIONAL AND IN FIRST OF LETTER OF PART NO., SUCH AS 94898-020MLF IS LOW COST VERSION 94898-020LF IS NOT LOW COST VERSION.

mat'l. code				surface ISO 1302	tolerance ISO 406 ISO 1101	projection	product family PCMCIA
ltr	ecn no	dr	date	tolerances unless otherwise specified			title
P				angles ±2°	linear 0.X±0.3 / 0.XX±0.13 / 0.XXX±0.05	MM	68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE
				dr M.Hasegawa 2/24/05		scale 1:1	
				engr M.Hasegawa 2/24/05			dwg no 94898 sheet 3 of 7 size A4
				chr			
				appd			type CUSTOMER Drawing
sheet index	revision sheet						

PRODUCT NO.
94898-005
94898-005LF
94898-045
94898-045LF





NOTES

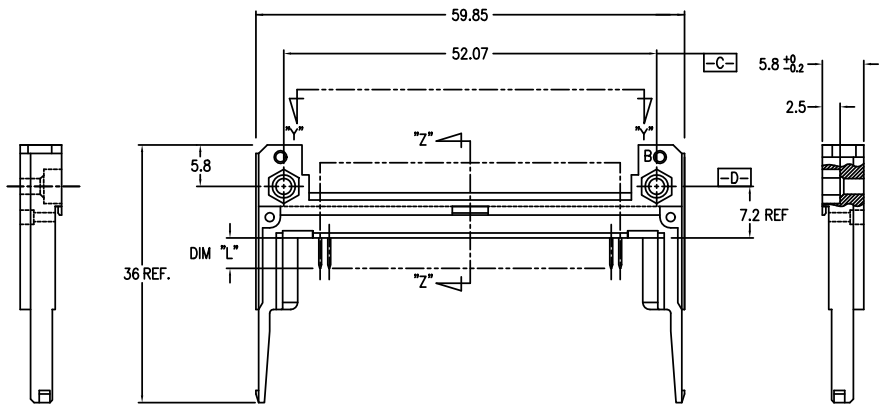
1. TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
2. SEE TA-946 FOR PCB LAYOUT.
3. MATERIAL
   HOUSING : HIGH TEMPERATURE THERMOPLASTIC
   PIN : COPPER ALLOY.
   HOLD-DOWN : BRASS
4. FINISH
   PIN
   UNDER PLATING : 0.5um MIN. Ni.
   CONTACT AREA : 0.1um MIN. Au.
   OVER 0.5um MIN. Pd-Ni.
   SOLDER AREA : 2.5um MIN. Sn-Pb.
   OR 2.5um MIN. PURE Sn.(FOR -XXXLF)
   HOLD-DOWN : 2.5um MIN. PURE Sn.
5. RECOMMENDED PCB HOLE (OPTIONAL HOLD-DOWN) : 2.3±0.1
6. SEQUENCE PIN ASSIGNMENT

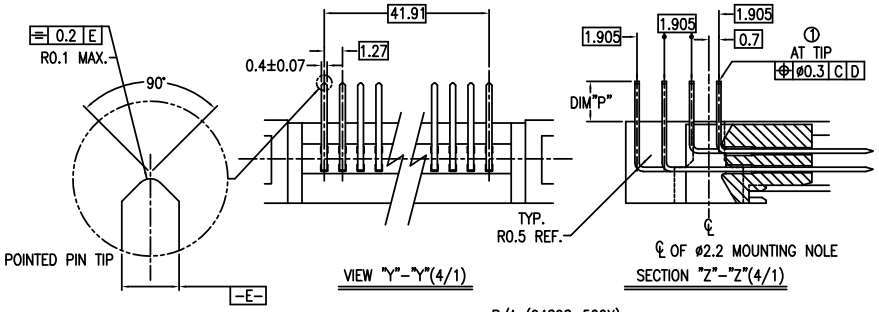
	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
PIN No.	OTHERS	36.67	1,17,34 35,51,68

7. GENERAL TOLERANCE : ±0.3
8. SEE SHEET 1 REGARDING COMPONENTS.
9. IF LEAD FREE P/N,THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
10. LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
11. IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION

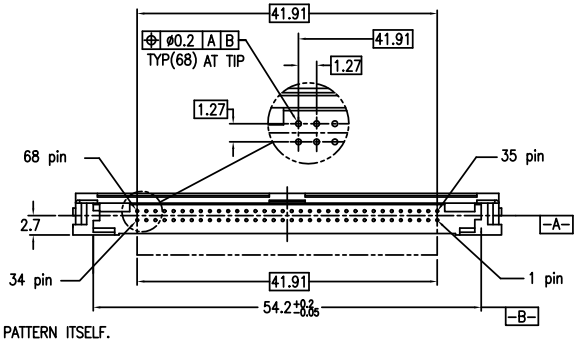
mat'l. code	surface ISO 1302	tolerance ISO 406 ISO 1101	projection	product family: PCMCIA
ltr / ecn no / dr / date: P	tolerances unless otherwise specified			title: 68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE
	angles ±2°	linear 0.X±0.3 / 0.XX±0.13 / 0.XXX±0.05	MM, scale 1:1	
	dr M.Hasegawa 2/24/'05			dwg no 94898, sheet 4 of 7, size A4
	engr M.Hasegawa 2/24/'05			
	chr			
	appd			type CUSTOMER Drawing
sheet index	revision sheet			

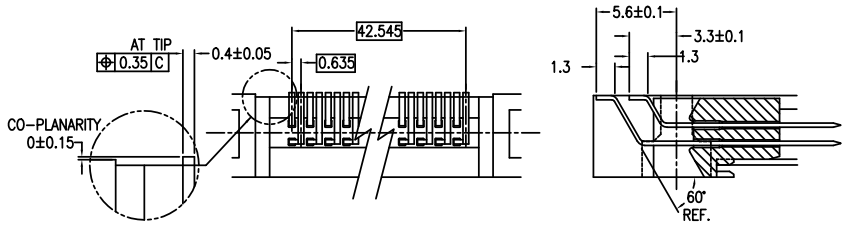
PRODUCT NO.	
94898-500	
94898-500LF	
94898-500H	
94898-500HLF	
94898-501	
94898-501LF	
94898-501H	
94898-501HLF	
94898-502	
94898-502J	—SEE NOTE 12
94898-502LF	
94898-502H	
94898-502HLF	



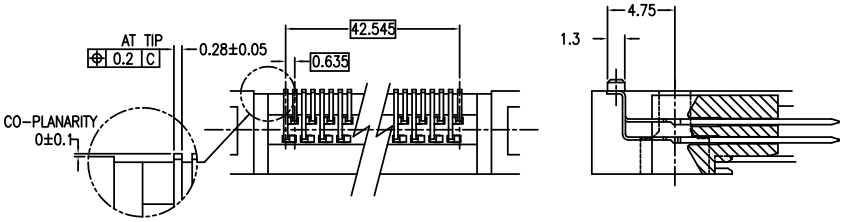


R/A (94898-500X)





SMT STAGGERED (94898-501X)



SMT IN LINE (94898-502X)

NOTES

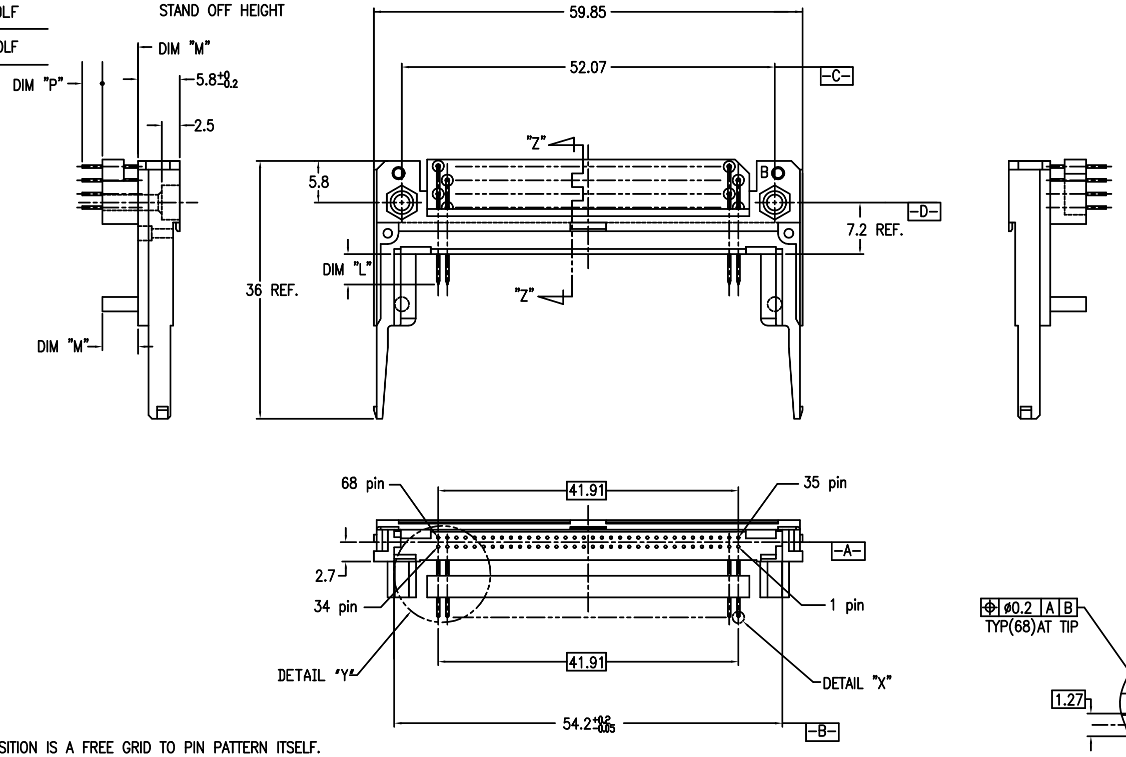
○1. TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
2. SEE TA-946 FOR PCB LAYOUT.
③ MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC
PIN : COPPER ALLOY.
HOLD-DOWN : BRASS
④ FINISH
PIN
UNDER PLATING : 0.5um MIN. Ni.
CONTACT AREA : 0.1um MIN. Au.
OVER 0.5um MIN. Pd-Ni.
SOLDER AREA : 2.5um MIN. Sn-Pb.
OR 2.5um MIN. PURE Sn.(FOR -XXXLF)
HOLD-DOWN : 2.5um MIN. PURE Sn.
5. RECOMMENDED PCB HOLE (OPTIONAL HOLD-DOWN) : 2.3±0.1
6. SEQUENCE PIN ASSIGNMENT

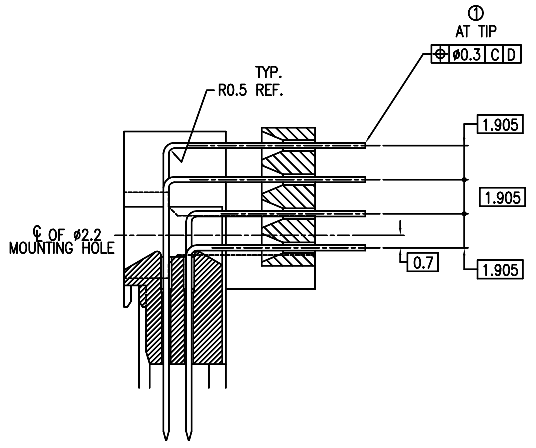
	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
PIN No.	OTHERS	36.67	1,17,34 35,51,68

7. GENERAL TOLERANCE : ±0.3
8. SEE SHEET 1 REGARDING COMPONENTS.
9. IF LEAD FREE P/N,THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
10. LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
11. IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION
⑫ THE P/N 94898-502J HAS SPECIAL TRAY, IT IS 10084720-001.

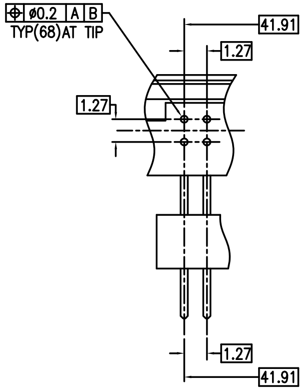
mat'l. code				surface	tolerance	projection	product family
				ISO 1302	ISO 406 ISO 1101		PCMCIA
ltr	ecn no	dr	date	tolerances unless otherwise specified			title
P				angles	0.X±0.3	MM	68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE
				linear	0.XX±0.13		
				±2°	0.XXX±0.05	scale 1:1	
				dr M.Hasegawa 2/24/'05			dwg no 94898 sheet 5 of 7 size A4
				engr M.Hasegawa 2/24/'05			
				chr			type CUSTOMER Drawing
				appd			
sheet index	revision sheet						

PRODUCT NO.	
94898-510	94898-510LF
94898-520	94898-520LF
94898-530	94898-530LF
94898-540	94898-540LF

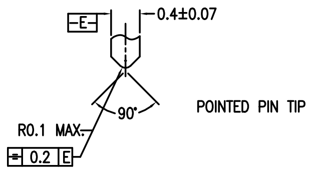




SECTION "Z"-"Z" (5/1)



DETAIL "Y" (5/1)



DETAIL "X" (20/1)
TYP(68)

NOTES

① TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
2. SEE TA-946 FOR PCB LAYOUT.
③ MATERIAL
   HOUSING : HIGH TEMPERATURE THERMOPLASTIC
   PIN : COPPER ALLOY.
   HOLD-DOWN : BRASS
④ FINISH
   PIN
   UNDER PLATING : 0.5um MIN. Ni.
   CONTACT AREA : 0.1um MIN. Au.
   OVER 0.5um MIN. Pd-Ni.
   SOLDER AREA : 2.5um MIN. Sn-Pb.
   OR 2.5um MIN. PURE Sn.(FOR -XXXLF)
   HOLD-DOWN : 2.5um MIN. PURE Sn.
5. RECOMMENDED PCB HOLE (OPTIONAL HOLD-DOWN) : 2.3±0.1
6. SEQUENCE PIN ASSIGNMENT

	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
PIN No.	OTHERS	36,67	1,17,34 35,51,68

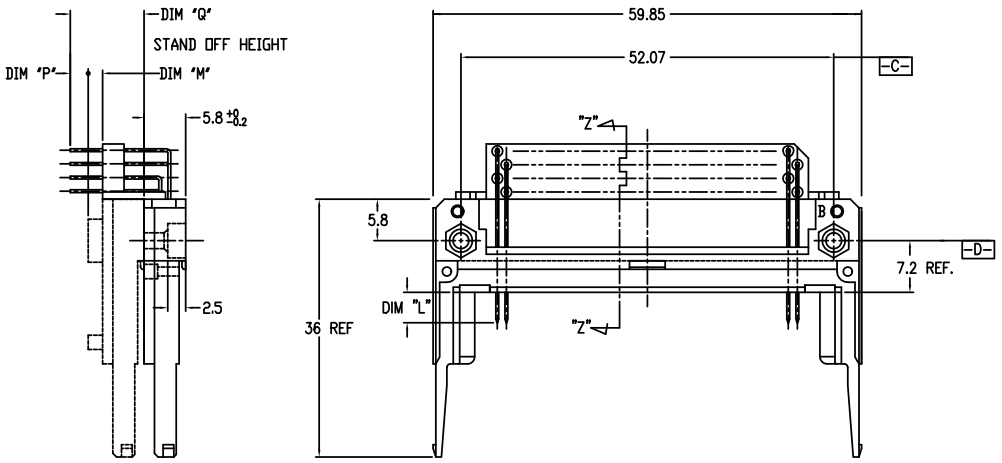
7. GENERAL TOLERANCE : ±0.3
8. SEE SHEET 1 REGARDING COMPONENTS.
9. IF LEAD FREE P/N,THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
10. LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
11. IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION

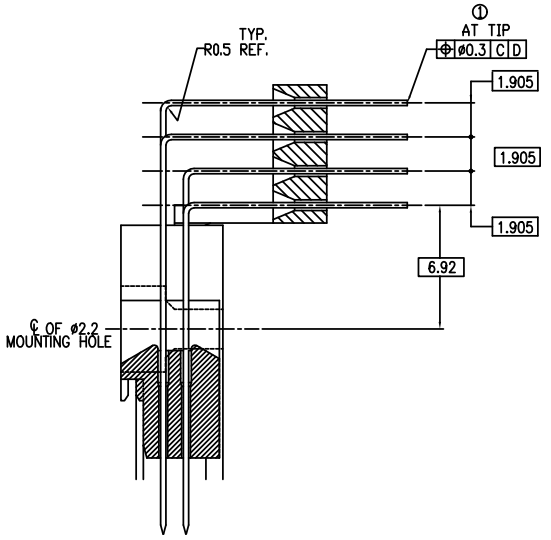
mat'l. code
surface ISO 1302
tolerance ISO 406 ISO 1101
projection
product family: PCMCIA
ltr | ecn no | dr | date
P
tolerances unless otherwise specified
angles ±2°
linear 0.X±0.3 / 0.XX±0.13 / 0.XXX±0.05
MM
scale 1:1
title: 68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE
dr M.Hasegawa 2/24/'05
engr M.Hasegawa 2/24/'05
chr
appd
dwg no 94898
sheet 6 of 7
size A4
type CUSTOMER Drawing
sheet index
revision sheet

form: A3

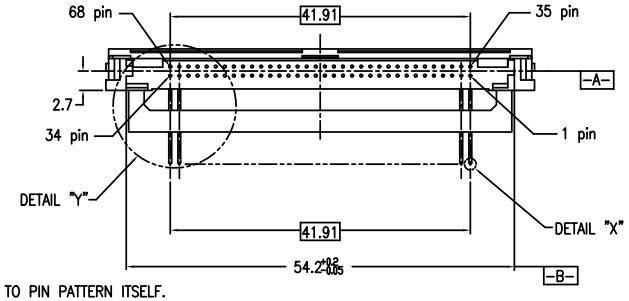
PDS: Rev :P STATUS: Released Printed: Dec 19, 2011

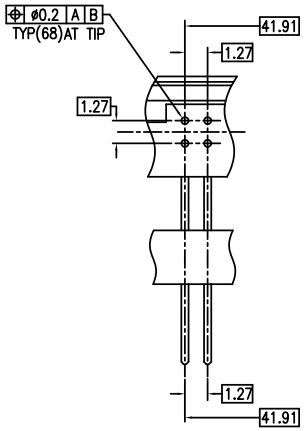
PRODUCT NO.
94898-505
94898-505LF
94898-535
94898-535LF
94898-545
94898-545LF



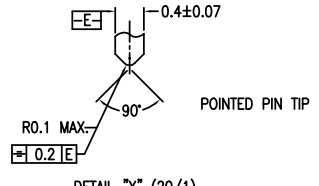


SECTION "Z"-"Z" (5/1)





DETAIL "Y" (5/1)



DETAIL "X" (20/1)
TYP(68)

NOTES
① TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
2. SEE TA-946 FOR PCB LAYOUT.
③ MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC
PIN : COPPER ALLOY.
HOLD-DOWN : BRASS
④ FINISH
PIN
UNDER PLATING : 0.5um MIN. Ni.
CONTACT AREA : 0.1um MIN. Au.
OVER 0.5um MIN. Pd-Ni.
SOLDER AREA : 2.5um MIN. Sn-Pb.
OR 2.5um MIN. PURE Sn.(FOR -XXXLF)
HOLD-DOWN : 2.5um MIN. PURE Sn.
5. RECOMMENDED PCB HOLE (OPTIONAL HOLD-DOWN) : 2.3±0.1
6. SEQUENCE PIN ASSIGNMENT

	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
PIN No.	OTHERS	36.67	1.17-34 35.51-68

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mat'l. code				surface ISO 1302	tolerance ISO 406 ISO 1101	projection	product family: PCMCIA	
ltr	ecn no	dr	date	tolerances unless otherwise specified			title: 68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE	
P				angles ±2°	linear 0.X±0.3 / 0.XX±0.13 / 0.XXX±0.05	MM		
						scale 1:1		
				dr M.Hasegawa 2/24/'05			dwg no 94898	sheet 7 of 7 size A4
				engr M.Hasegawa 2/24/'05				
				chr			type CUSTOMER	Drawing
				appd				
sheet index	revision sheet							